1. A sensor module, comprising:

(a) a housing having at least one interior wall surface;

(b) a CCD sensor unit disposed at least partially within said housing, and

(c) a plate-like carrier unit disposed between said wall surface and said sensor unit.

2. A sensor module as claimed in claim 1, wherein said plate-like carrier unit has a thermal expansion coefficient which substantially equals the thermal expansion of said CCD sensor unit.

3. A sensor module as claimed in claim 1, wherein said plate-like carrier unit is formed, at least in part, of aluminum nitride (AlN).

4. A sensor module as claimed in claim 3, wherein said plate-like carrier unit is fixed to said housing by means of a quasi-punctiform connection.

5. A sensor module as claimed in claim 1, wherein said carrier unit is fixed to said housing by at least one of, an adhesively bonded joint, and a soldered joint.

6. A sensor module as claimed in one of claim 1, further comprising a gap formed between said carrier unit and said housing.

7. A sensor module as claimed in claim 1, wherein said CCD sensor unit is fixed to said carrier unit by at least one of, an adhesively bonded joint, and a soldered joint.

8. A sensor module as claimed in claim 1, wherein said housing further includes a glass plate.

9. A sensor module as claimed in claim 8, wherein said glass plate hermetically seals the interior of said housing.

10. A sensor module as claimed in claim 8, wherein the respective coefficients of thermal expansion of said glass plate and said housing differ by less than $5 \times 10^{-6} \cdot K^{-1}$.

11. A sensor module as claimed in claim 1, wherein the housing comprises a PGA housing.

12. A sensor module as claimed in claim 1, wherein at least a portion of said housing is formed of Al_2O_3.